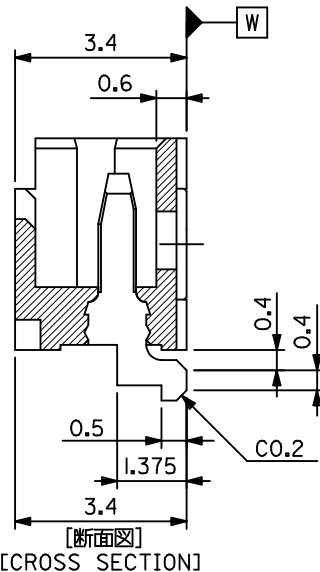
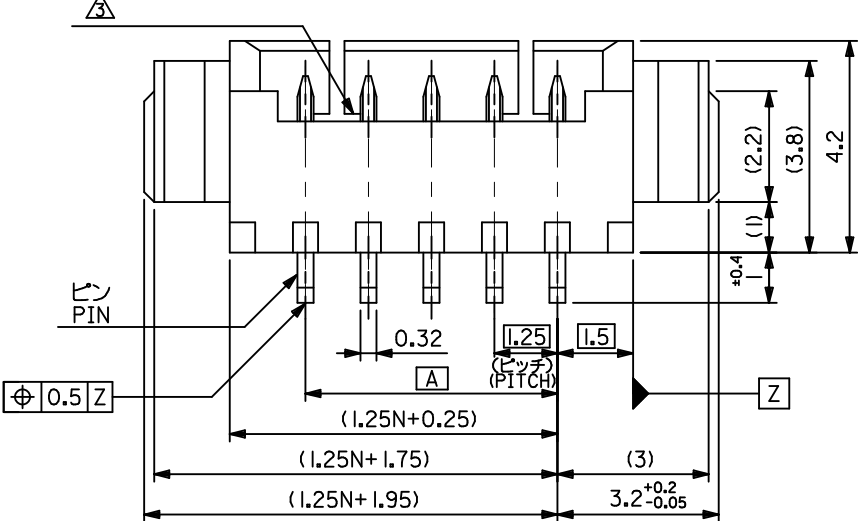
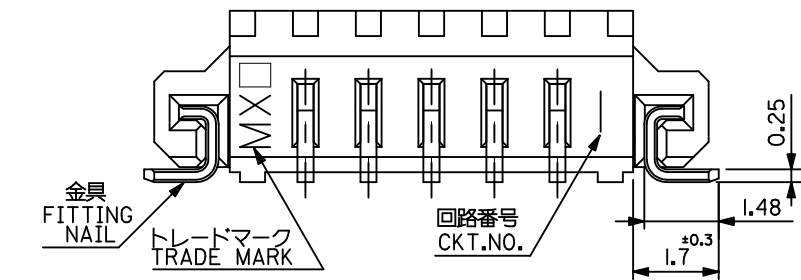


注記 NOTES

1. 嵌合相手: 51021 シリズ
MATES WITH: 51021 SERIES
2. 材質 MATERIAL
ウエハー: NYLON46, UL94V-0
ピン: リン青銅, 半田メッキ
PIN: PHOS-BRO., Sn-Pb(9:1) 3 μmMIN.
OVER Cu 1 μmMIN.
PLATING
金具: リン青銅, 半田メッキ
FITTING NAIL: PHOS-BRO., Sn-Pb(9:1) 2 μmMIN.
OVER Cu 1 μmMIN.
PLATING
- △ ロック窓は2、3極は1箇所、4極以上は2箇所とする。
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CKT. AND TWO PLACES FOR MORE THAN 3 CKT.
4. ソルダテール部のズレ量及び金具(補強板)のズレ量は基準面 W に対し、上方向 0.05 MAX.、下方向に 0.1 MAX. とする。
OFFSET BETWEEN BASIS PLANE W TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM: UPPER SIDE: 0.05MAX. LOWER SIDE: 0.1MAX.

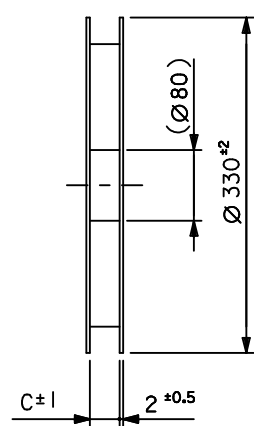
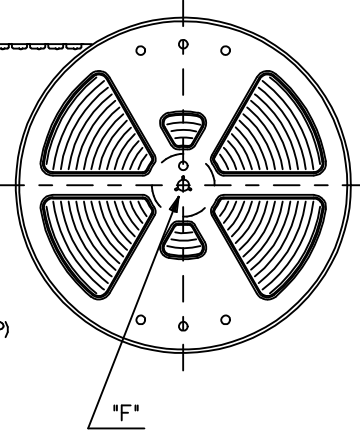


23.9	23.5	20.5	19.3	17.5	53261-1510	15
22.65	22.25	19.25	18.05	16.25	-1410	14
21.4	21	18	16.8	15	-1310	13
20.15	19.75	16.75	15.55	13.75	-1210	12
18.9	18.5	15.5	14.3	12.5	-1110	11
17.65	17.25	14.25	13.05	11.25	-1010	10
16.4	16	13	11.8	10	-0910	9
15.15	14.75	11.75	10.55	8.75	-0810	8
13.9	13.5	10.5	9.3	7.5	-0710	7
12.65	12.25	9.25	8.05	6.25	-0610	6
11.4	11	8	6.8	5	-0510	5
10.15	9.75	6.75	5.55	3.75	-0410	4
8.9	8.5	5.5	4.3	2.5	-0310	3
7.65	7.25	4.25	3.05	1.25	53261-0210	2
E	D	C	B	A	ENG. NO.	極数 CKT.



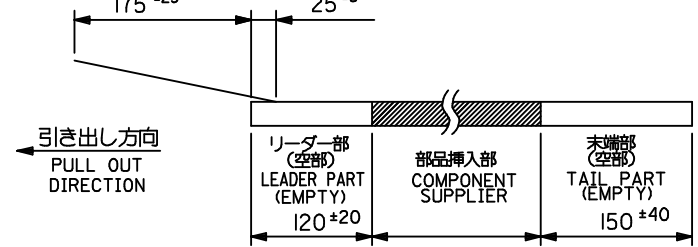
REVISED EC NO: J2012-1315 2012/04/17 DRWN: NITO CHKD: KASAKAWA 2012/04/17 APPR: YOITO 2012/04/26	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY NITO	DATE 2012/04/17	TITLE 1.25 WIRE TO BOARD WAFER ASS FOR SMT RIGHT ANGLE		
	10 OVER 30 UNDER	±0.25	CHECKED BY KASAKAWA	DATE 2012/04/17			
	30 OVER	±0.3	APPROVED BY YOITO	DATE 2012/04/26			
ANGULAR ±3 °		MATERIAL NO. SEE DRAWING		DOCUMENT NO. SD-53261-054		SHEET NO. 1 OF 1	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

引き出し方向
PULL OUT DIRECTION



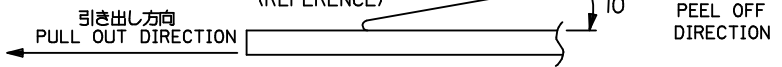
注記
NOTES

- 53261-**-10 の詳細寸法については図面 SD-53261-**-10 を参照下さい。
RE DETAILED DIMENSIONS, SEE SD-53261-**-10.
- 梱包数量: 1000個/リール
NUMBER OF CONNECTOR: 1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH
トップテープリーダ部 TOP TAPE LEADER PART 175 ± 25
トップテープ未接着部 TOP TAPE NON-BONDED PART 25 ± 5



- トップテープの剥離強度: 0.1N ~ 0.59N (10.2 ~ 60gf) (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE: 0.1N ~ 0.59N (10.2 ~ 60gf)
(PEELING DIRECTION IS SHOWN IN FOLLOWING FIG.)

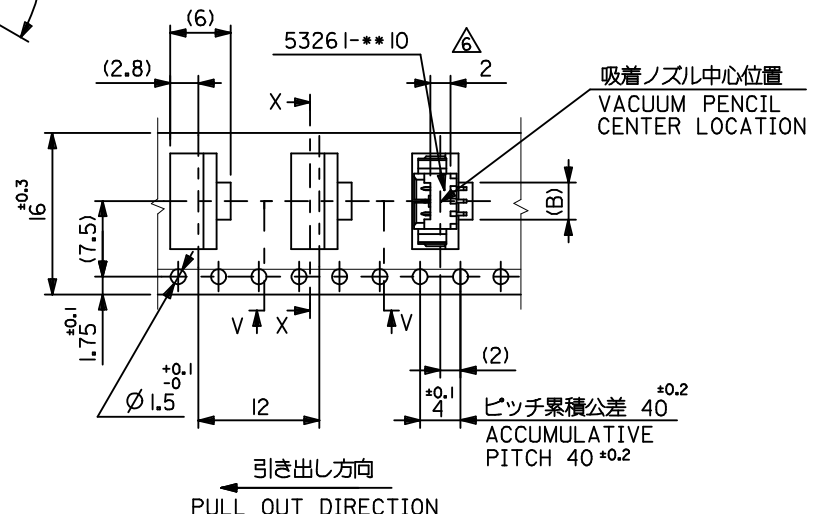
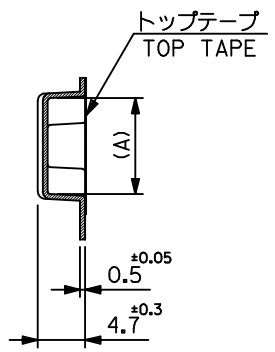
<剥離速度: 300mm/min (参考)>
PEELING SPEED: 300mm/min. (REFERENCE)



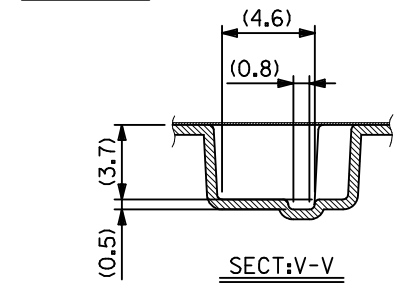
- 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)
トップテープ (TOP TAPE): PET, PE, PEF
リール (REEL): ポリスチレン (PS) <リサイクル材含む>
POLYSTYREN (PS) <RECYCLE MATERIAL CONTAINED>

△ コネクタ、ハウジング平面部
CONNECTOR, HOUSING FLAT AREA

DETAIL "F"



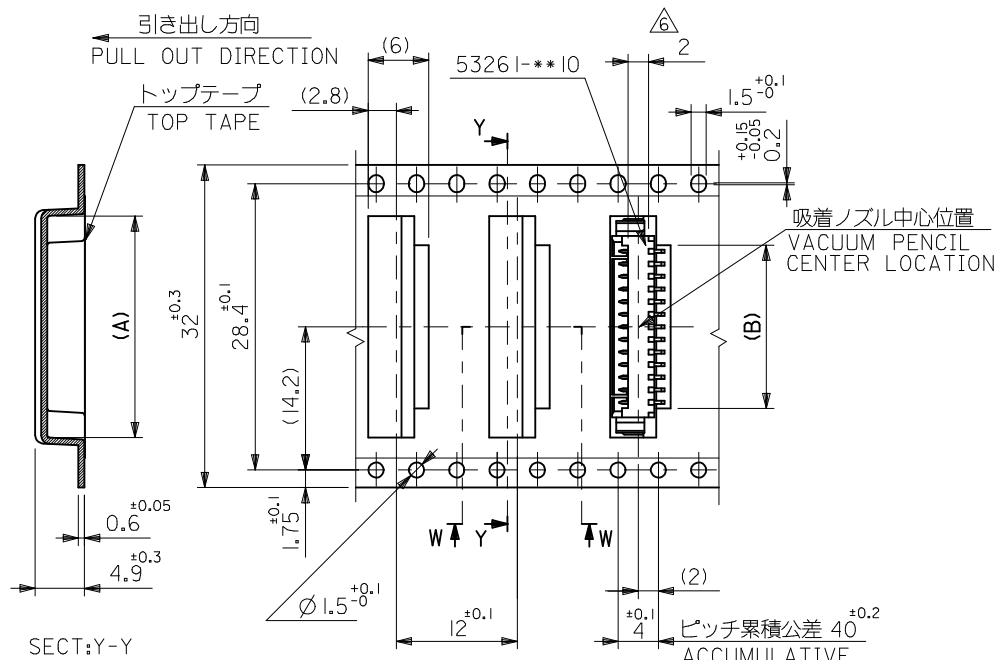
SECT:X-X



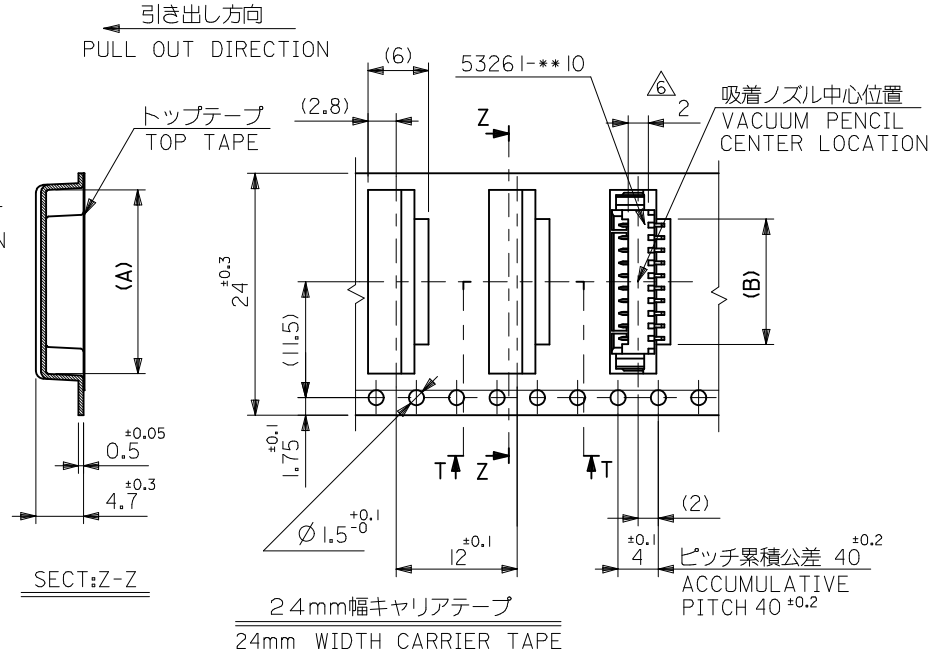
16mm幅キャリアテープ
16mm WIDTH CARRIER TAPE

16	16.4	3.7	9.5	53261-0390	3
		2.45	8.25	53261-0290	2
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	A	ENG. NO.	極数 CKT.

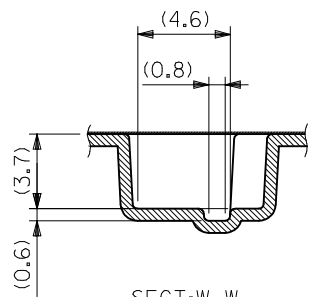
REVISED EC NO: J2014-1616 DRWN: TYAJIMA01 2014/04/28 CHKD: KASAKAWA 2014/04/28 APPR: NUKITA 2014/04/30	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY TYAJIMA01	DATE 2014/04/28	TITLE 1.25 W/B CONN. WAFER ASSY FOR SMT. EMBOSSED TAPE PACKAGE			
		10 OVER 30 UNDER	± ---	CHECKED BY KASAKAWA	DATE 2014/04/28				
		30 OVER	± ---	APPROVED BY	DATE				
		ANGULAR	± --- °	MATERIAL NO. SEE NOTES	DOCUMENT NO. SD-53261-055	SHEET NO. 1 OF 3			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



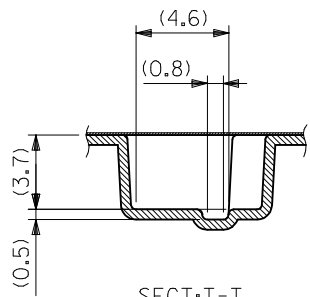
32mm幅キャリアテープ
32mm WIDTH CARRIER TAPE



24mm幅キャリアテープ
24mm WIDTH CARRIER TAPE



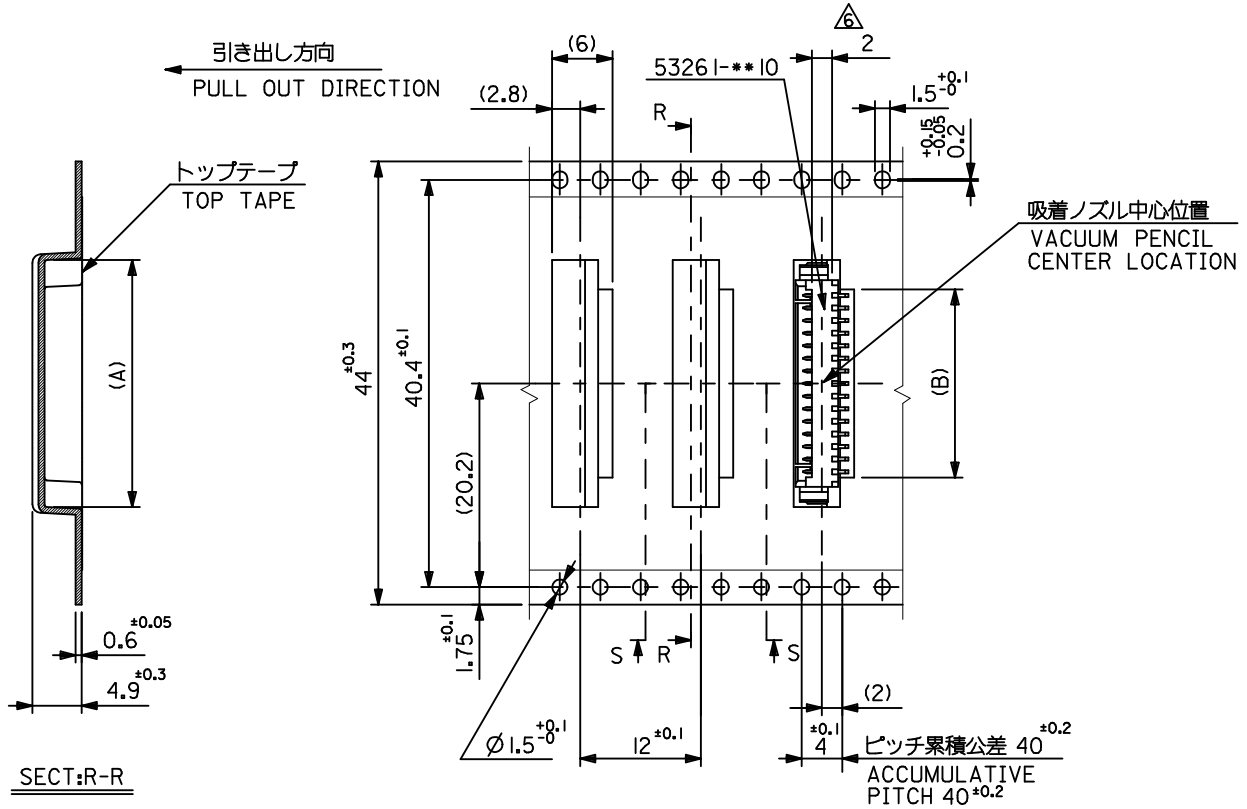
SECT:W-W



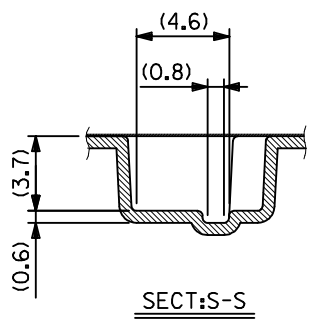
SECT:T-T

32	32.4	16.2	22	53261-1390	13
		14.95	20.75	-1290	12
24	24.4	13.7	19.5	-1190	11
		12.45	18.25	-1090	10
		11.2	17	-0990	9
		9.95	15.75	-0890	8
		8.7	14.5	-0790	7
		6.2	12	-0590	5
		4.95	10.75	53261-0490	4
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	A	ENG. NO.	極数 CKT.

REVISED EC NO: J2014-1616 DRWN:TYAJIMA01 2014/04/28 CHKD:KASAKAWA 2014/04/28 APPR:NUKITA 2014/04/30	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY TYAJIMA01	DATE 2014/04/28	TITLE 1.25 W/B CONN. WAFER ASSY FOR SMT. EMBOSSED TAPE PACKAGE				
		10 OVER 30 UNDER	± ---	CHECKED BY KASAKAWA	DATE 2014/04/28					
		30 OVER	± ---	APPROVED BY NUKITA	DATE 2014/04/30					
ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE NOTES		DOCUMENT NO. SD-53261-055		SHEET NO. 2 OF 3		
SIZE A3				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



SECT:R-R



SECT:S-S

44mm幅キャリアテープ
44mm WIDTH CARRIER TAPE

44	44.4	18.7	24.5	53261-I590	15
		17.45	23.25	53261-I490	14
キャリアテープ幅 CARRIER TAPE WIDTH	C	B	A	ENG. NO.	種数 CKT.

REVISED EC NO: J2014-1616 DRWN: TYAJIMA01 CHKD: KASAKAWA APPR: NUKITA	DESCRIPTION 2014/04/28 2014/04/28 2014/04/30	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY TYAJIMA01	DATE 2014/04/28	TITLE 1.25 W/B CONN. WAFER ASSY FOR SMT. EMBOSSED TAPE PACKAGE				
		10 OVER 30 UNDER	± ---	CHECKED BY KASAKAWA	DATE 2014/04/28					
		30 OVER	± ---	APPROVED BY NUKITA	DATE 2014/04/30					
REV	DESCRIPTION	ANGULAR	± --- °	MATERIAL NO. SEE NOTES	DOCUMENT NO. SD-53261-055	SHEET NO. 3 OF 3				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						